



Low Quiescent Current, Dual-Channel Supervisory Circuit

FEATURES

- Two Supply Monitors in One Package
- One Monitor with Fixed High-Accuracy Thresholds for System Supply Monitoring
- Second Monitor with Variable Threshold and 30mV Hysteresis to Provide Failsafe
- Very Low Quiescent Current: 3.5µA typ
- High Threshold Accuracy: 1% max (0°C to +85°C)
- Open-Drain Reset Outputs
- Temperature Range: –40°C to +85°C
- Ultra-Small SC70-5 Package

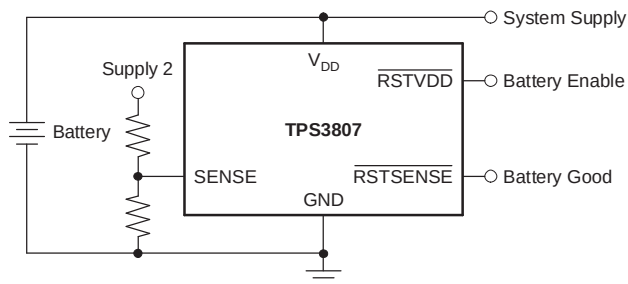
APPLICATIONS

- DSP, Microcontroller, or Microprocessor Applications Requiring User-Selected Delay Times
- Notebook/Desktop Computers
- PDAs and Smartphones
- Other Hand-Held Products
- Portable, Battery-Powered Products
- FPGA/ASIC Applications

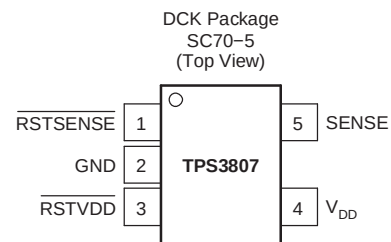
DESCRIPTION

The TPS3807 family microprocessor supervisory circuits monitor system voltages as low as 1.225V. These devices assert an open-drain $\overline{\text{RSTVDD}}$ signal when the V_{DD} voltage drops below a preset threshold. The $\overline{\text{RSTVDD}}$ output remains asserted until the V_{DD} voltage returns above its threshold. The device also provides an additional $\overline{\text{RSTSENSE}}$ output for a SENSE input with adjustable thresholds and hysteresis.

The TPS3807 uses a precision reference to achieve 1% threshold accuracy. The TPS3807 has a very low typical quiescent current of 3.5µA, so it is well-suited to battery-powered applications. It is available in a small SC70-5 package, which is half the size of a SOT-23 package, and is fully specified over a temperature range of –40°C to +85°C.



Typical Application Circuit



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ORDERING INFORMATION⁽¹⁾

PRODUCT	V _{DD} NEGATIVE THRESHOLD VOLTAGE (V _{DD IT-}) ⁽²⁾	V _{DD} POSITIVE THRESHOLD VOLTAGE (V _{DD IT+}) ⁽²⁾	SENSE THRESHOLD VOLTAGE (V _{SENSE IT})
TPS3807A30DCKT ⁽³⁾	3.00V	3.58V	1.225V
TPS3807A30DCKR ⁽⁴⁾	3.00V	3.58V	1.225V

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document or see the TI web site at www.ti.com.

(2) Other voltage options are available upon request; minimum order quantities may apply.

(3) DCKT passive indicates tape and reel containing 250 parts.

(4) The DCKR passive indicates tape and reel containing 3000 parts.

ABSOLUTE MAXIMUM RATINGS

Over operating free-air temperature range, unless otherwise noted.⁽¹⁾

SENSE pin voltage ⁽²⁾	–0.3V to +5V
MR	–0.3V to V _{DD} +0.3V
RESET	–0.3V to V _{DD} +0.3V
All other pins ⁽²⁾	–0.3V to +7V
Maximum output current	±5mA
Input clamp current, I _{IK} (V _{SENSE} < 0 or V _{SENSE} > V _{DD})	±10mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±10mA
Continuous total power dissipation	See <i>Dissipation Ratings</i> table
Junction temperature, T _C	–40°C to +125°C
Storage temperature range, T _{STG}	–65°C to +150°C
Soldering temperature	+260°C
ESD rating:	
Human body model (HBM)	2kV
Charged device model (CDM)	500V

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7V for more than t = 1000 hours.

DISSIPATION RATINGS

PACKAGE	θ _{JA}	DERATING FACTOR ABOVE T _A = +25°C	T _A < +25°C POWER RATING	T _A = +70°C POWER RATING	T _A = +80°C POWER RATING
DCK	+246°C/W	2.6mW/°C	406mW	223mW	167mW

RECOMMENDED OPERATING CONDITIONS

		MIN	MAX	UNIT
Supply voltage, V _{DD}		1.8	6.5	V
Input voltage, V _{SENSE}	0V ≤ V _{DD} ≤ 4.2V	0	V _{DD} + 0.3	V
	V _{DD} ≥ 4.2V		4.5	
Operating free-air temperature range, T _A		–40°C	+85°C	°C

ELECTRICAL CHARACTERISTICS

Over recommended operating temperature range, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{DD}	Input supply range		1.8		6.5	V
I _{DD}	Supply current	V _{DD} = 3.3V $\overline{\text{RSTVDD}}$, $\overline{\text{RSTSENSE}}$ = open		3.5	6.5	μA
		V _{DD} = 6.5V $\overline{\text{RSTVDD}}$, $\overline{\text{RSTSENSE}}$ = open		4.5	7.5	μA
V _{OL}	Low-level output voltage	V _{DD} = 1.3V, I _{OL} = 0.4mA			0.3	V
		V _{DD} = 1.8V, I _{OL} = 1mA			0.4	
		V _{DD} = 3.3V, I _{OL} = 2mA			0.4	
	Power-up reset ⁽¹⁾	V _{$\overline{\text{RSTVDD}}$} (max) = 0.2V, I _{OL} = 30μA, +25°C	0.9			V
V _{DD IT–}	Negative-going input threshold voltage ⁽²⁾		2.963	3.000	3.037	V
V _{DD IT+}	Positive-going input threshold voltage ⁽²⁾		3.530	3.575	3.620	V
V _{SENSE IT–}	Negative-going input threshold voltage	0°C to +85°C	1.213	1.225	1.237	V
		–40°C to +85°C	1.210	1.225	1.240	
V _{HYS}	SENSE input hysteresis			30		mV
I _{SENSE}	Input current		–25		+25	nA
C _I	Input capacitance	V _I = 0V to V _{DD}		1		pF
I _{OH}	High-level output current	V _{$\overline{\text{RSTVDD}}$} , $\overline{\text{RSTSENSE}}$ = 6.5V			300	nA

(1) The lowest supply voltage at which $\overline{\text{RSTVDD}}$ (V _{$\overline{\text{RSTVDD}}$} (max) = 0.2V, I_{OL} = 30μA) becomes active. t_r, V_{DD} ≥ 15μs/V.

(2) To ensure best stability of the threshold voltage, a bypass capacitor (ceramic, 0.1μF) should be placed near the V_{DD} pin.

TIMING REQUIREMENTS

At T_A = –40°C to +85°C, R_L = 1MΩ, and C_L = 50pF, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _W	Pulse width	V _{IH} = 1.05V _{IT} , V _{IL} = 0.95V _{IT}	10			μs

SWITCHING CHARACTERISTICS

At T_A = –40°C to +85°C, R_L = 1MΩ, and C_L = 50pF, unless otherwise noted.

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PHL}	Propagation delay time, high-to-low-level output	V _{DD} to $\overline{\text{RSTVDD}}$		20		μs
		SENSE to $\overline{\text{RSTSENSE}}$				

FUNCTIONAL BLOCK DIAGRAM

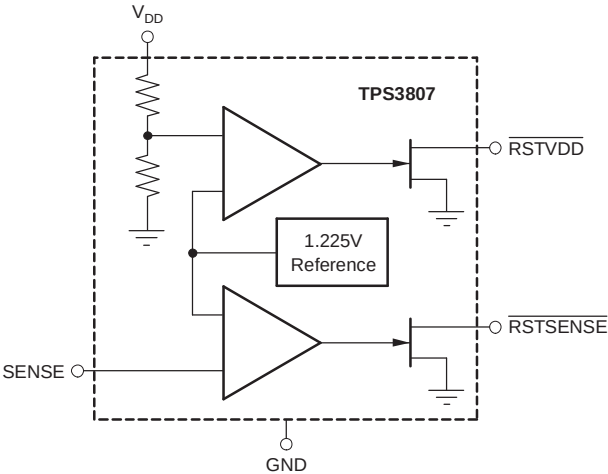


Table 1. PIN DESCRIPTIONS

NAME	PIN NO.	I/O	DESCRIPTION
$\overline{\text{RSTSENSE}}$	1	O	$\overline{\text{RSTSENSE}}$ is an open-drain output that is driven to a low-impedance state when the SENSE input is lower than the threshold voltage $V_{\text{SENSE IT-}}$. $\overline{\text{RSTSENSE}}$ will remain low until SENSE is above $V_{\text{SENSE IT+}}$. A pull-up resistor from 10k Ω to 1M Ω should be used on this pin, and allows the reset pin to attain voltages higher than V_{DD} .
GND	2	I	Ground
$\overline{\text{RSTVDD}}$	3	O	$\overline{\text{RSTVDD}}$ is an open-drain output that is driven to a low-impedance state when the V_{DD} input is lower than the threshold voltage $V_{\text{DD IT-}}$. $\overline{\text{RSTVDD}}$ will remain low until V_{DD} is above $V_{\text{DD IT+}}$. A pull-up resistor from 10k Ω to 1M Ω should be used on this pin, and allows the reset pin to attain voltages higher than V_{DD} .
V_{DD}	4	I	Supply voltage for the device and sense input for fixed-threshold $\overline{\text{RSTVDD}}$ outputs. A 0.1 μF ceramic capacitor should be placed close to this pin for best V_{IT} stability.
SENSE	5	I	Sense input for the adjustable-threshold $\overline{\text{RSTSENSE}}$ outputs. A resistor divider from the sense voltage can be attached to this pin to set the thresholds to the desired voltages. A 0.1 μF ceramic capacitor should be placed close to this pin for best V_{IT} stability.

TIMING DIAGRAM

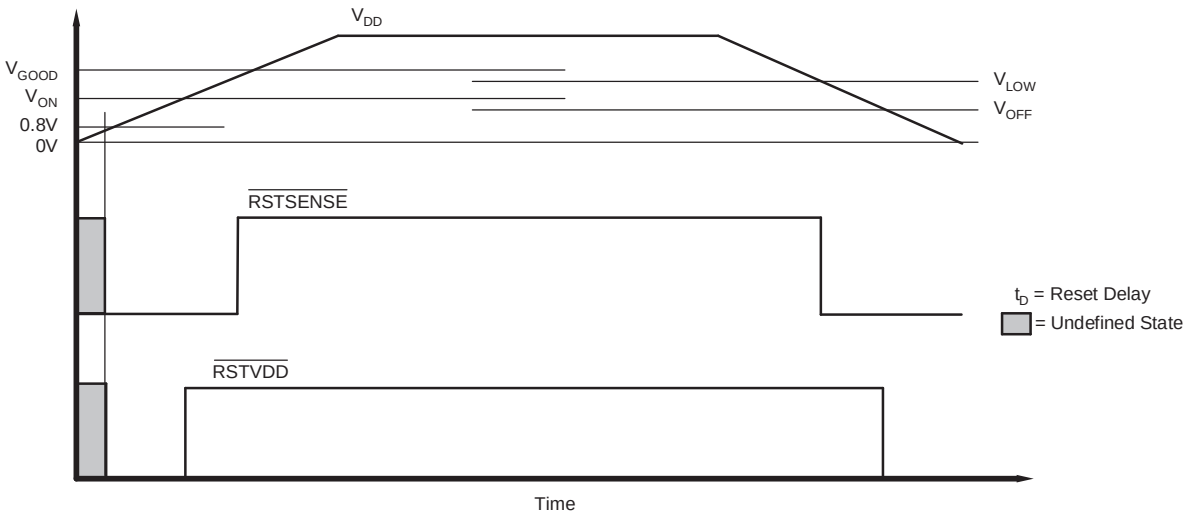
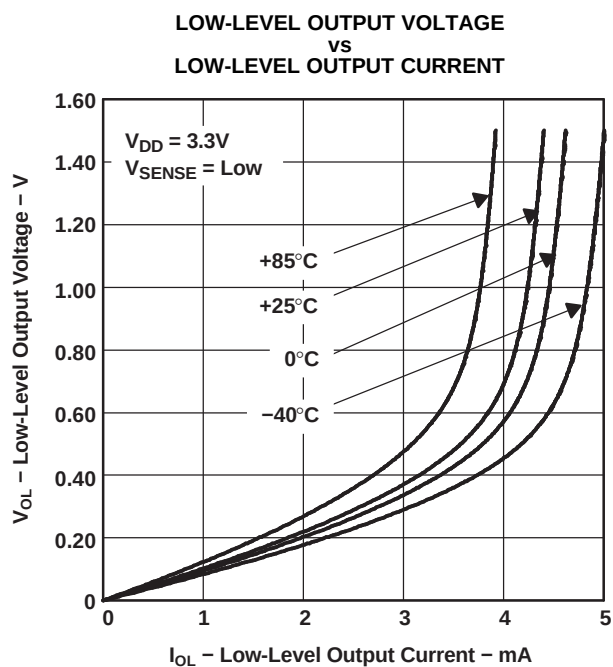
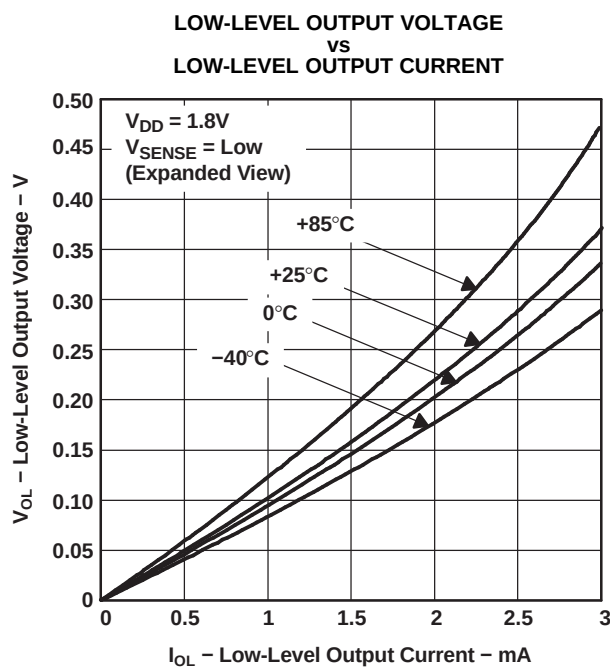
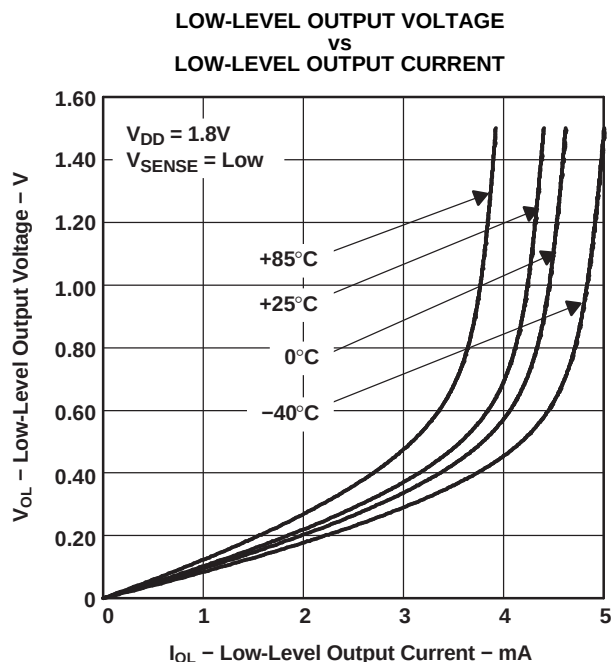
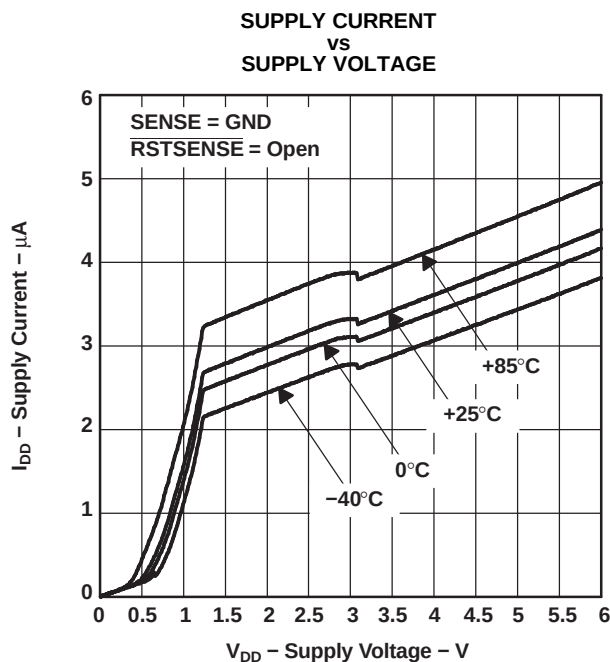


Figure 1. TPS3807 Timing Diagram Showing Reset Timing (SENSE resistor divider set to 3.6V)

TYPICAL CHARACTERISTICS

At $T_A = +25^\circ\text{C}$, $V_{DD} = 3.3\text{V}$, $R_{LRESET} = 1\text{M}\Omega$, and $C_{LRESET} = 50\text{pF}$, unless otherwise noted.



TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_{DD} = 3.3\text{V}$, $R_{LRESET} = 1\text{M}\Omega$, and $C_{LRESET} = 50\text{pF}$, unless otherwise noted.

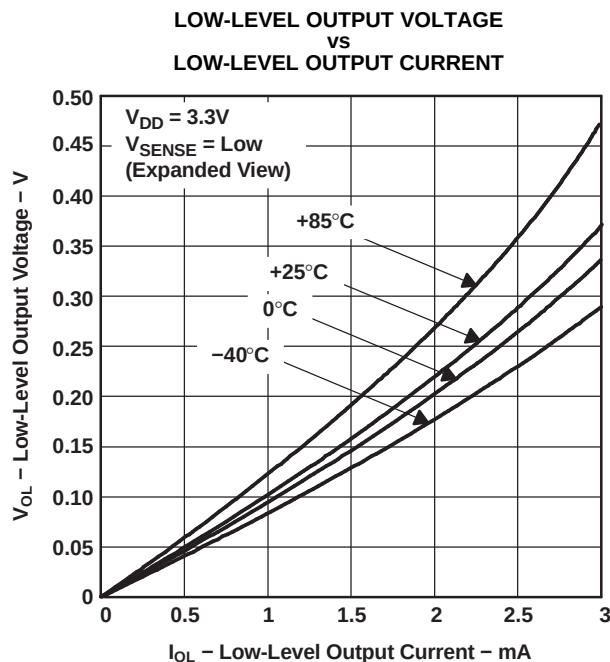


Figure 6.

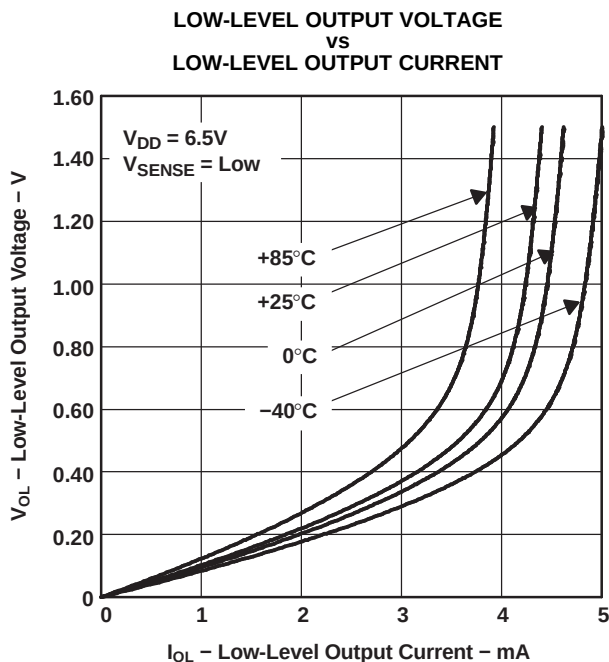


Figure 7.

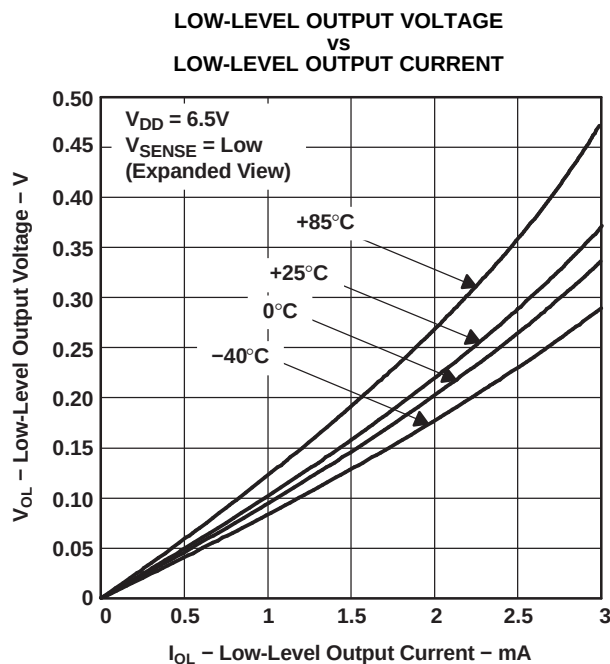


Figure 8.

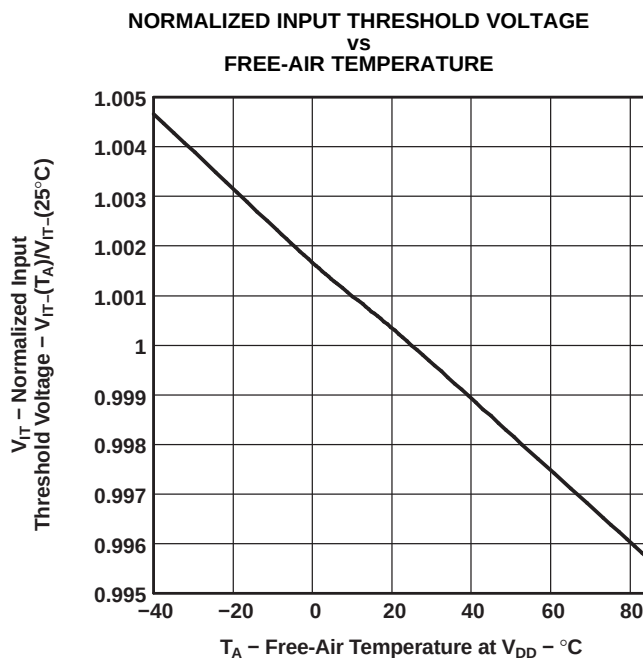


Figure 9.

TYPICAL CHARACTERISTICS (continued)

At $T_A = +25^\circ\text{C}$, $V_{DD} = 3.3\text{V}$, $R_{LRESET} = 1\text{M}\Omega$, and $C_{LRESET} = 50\text{pF}$, unless otherwise noted.

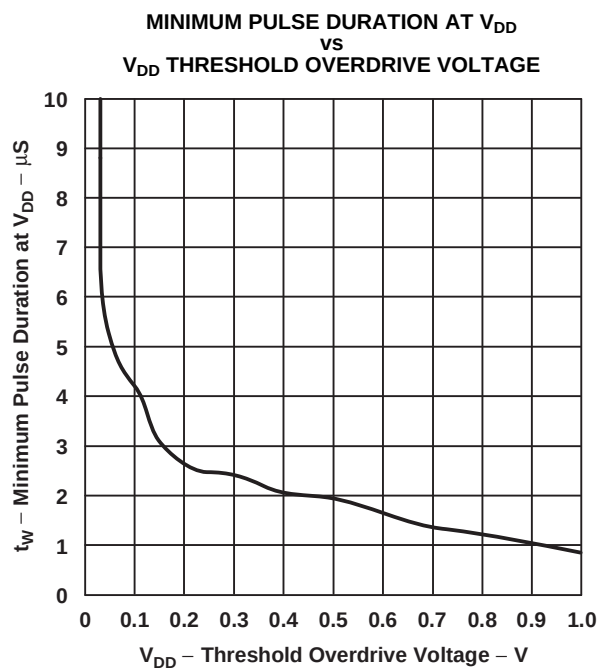


Figure 10.

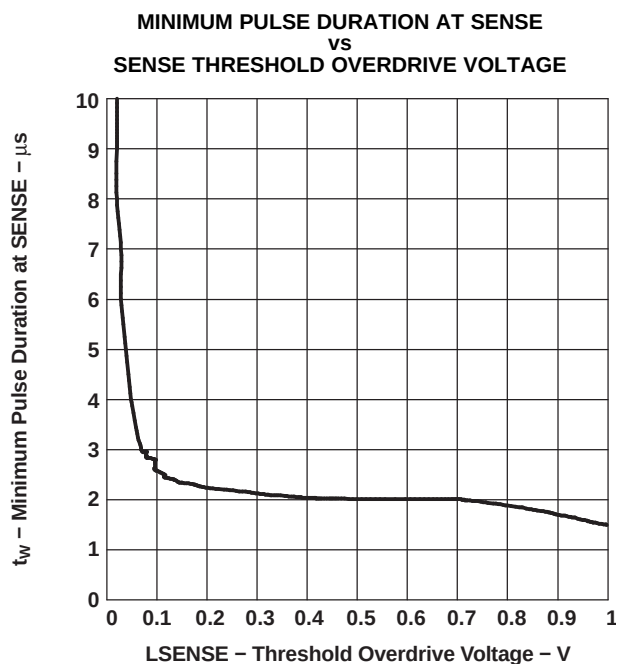


Figure 11.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS3807A30DCKR	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	BOM
TPS3807A30DCKR.B	Active	Production	SC70 (DCK) 5	3000 LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	BOM
TPS3807A30DCKT	Active	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	BOM
TPS3807A30DCKT.B	Active	Production	SC70 (DCK) 5	250 SMALL T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	BOM

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

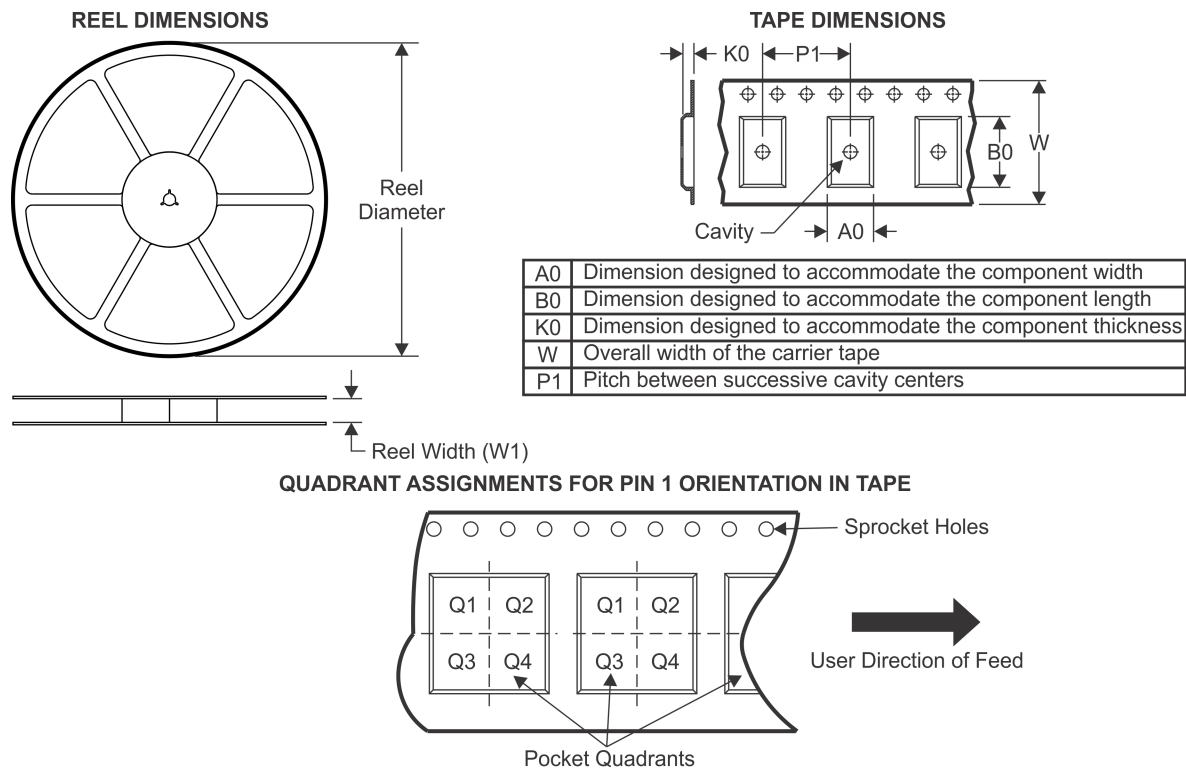
⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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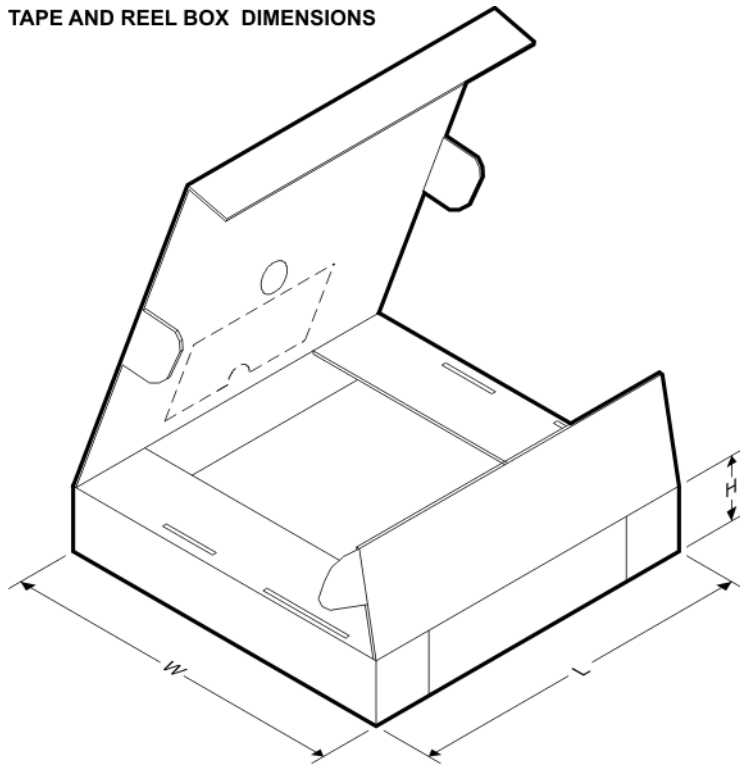
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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3807A30DCKR	SC70	DCK	5	3000	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3
TPS3807A30DCKT	SC70	DCK	5	250	180.0	8.4	2.41	2.41	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3807A30DCKR	SC70	DCK	5	3000	183.0	183.0	20.0
TPS3807A30DCKT	SC70	DCK	5	250	183.0	183.0	20.0



SOT - 1.1 max height

Technical drawing of a mechanical part showing three views: front, side, and top.

Front View Dimensions:

- Overall width: 2.4 (1.8)
- Overall height: 2.15 (1.85)
- Horizontal hole locations: 1.4 (1.1)
- Vertical hole locations: 1.3 (1.3)
- Hole sizes: 0.15 (0.1)
- Feature: NOTE 4
- Feature: PIN 1 INDEX AREA (hatched area)
- Feature: 2X 0.65
- Feature: 5X 0.33 0.15

Side View Dimensions:

- Width: 1.1 MAX
- Thickness: 0.1 C

Top View Dimensions:

- Width: 0.46 TYP
- Height: 0.22 TYP
- Feature: 4X 4° -15°
- Feature: 8° 0° TYP
- Feature: 0.22 0.08 TYP
- Feature: GAGE PLANE
- Feature: SEATING PLANE

Surface Texture Symbols:

- Front View: 0.1 (0.05) A B
- Top View: 0.1 (0.05) C A B

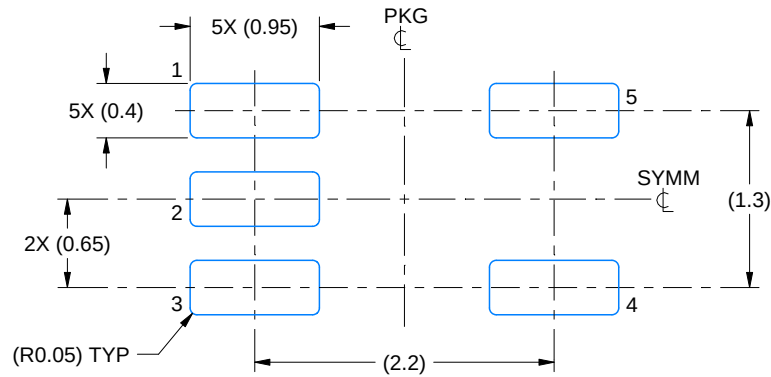
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-203.
4. Support pin may differ or may not be present.
5. Lead width does not comply with JEDEC.
6. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

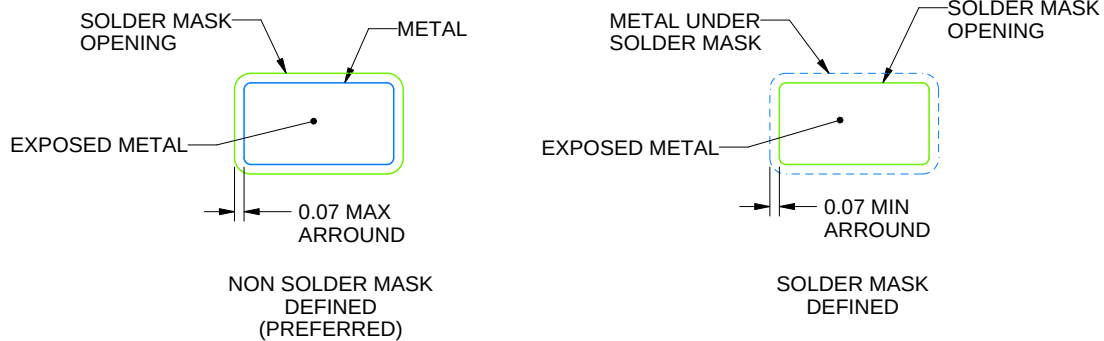
DCK0005A

SOT - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

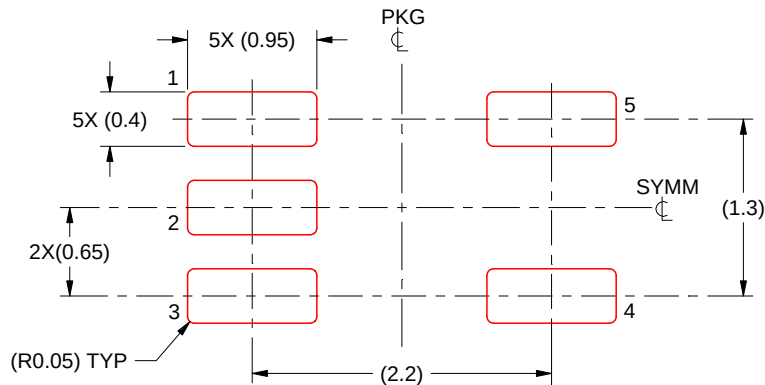


SOLDER MASK DETAILS

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NOTES: (continued)

7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214834/G 11/2024

NOTES: (continued)

9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
10. Board assembly site may have different recommendations for stencil design.

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